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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	C166SV2
Core Size	16-Bit
Speed	40MHz
Connectivity	CANbus, EBI/EMI, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	79
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 2.7V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100-5
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc164d-8f40f-bb

XC164D
Revision History: V1.2, 2006-08

Previous Version(s):
V1.1, 2006-03
V1.0, 2005-01

Page	Subjects (major changes since last revision)
6	New derivatives added.
11	Description of the $\overline{\text{TRST}}$ signal modified.
47	Instructions Set Summary improved.
50	Footnote added about pin XTAL1 belonging to V_{DDI} power domain.
54	Footnote added about amplitude at XTAL1 pin.
70	Thermal Resistance: R_{THA} replaced by $R_{\Theta\text{JC}}$ and $R_{\Theta\text{JL}}$ because R_{THA} strongly depends on the external system (PCB, environment). P_{DISS} removed, because no static parameter, but derived from thermal resistance.
71	Green Package added.

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mcdocu.comments@infineon.com

  - Programmable External Bus Characteristics for Different Address Ranges
  - Multiplexed or Demultiplexed External Address/Data Buses
  - Selectable Address Bus Width
  - 16-Bit or 8-Bit Data Bus Width
  - Four Programmable Chip-Select Signals
- Up to 79 General Purpose I/O Lines,
  partly with Selectable Input Thresholds and Hysteresis
- On-Chip Bootstrap Loader
- Supported by a Large Range of Development Tools like C-Compilers, Macro-Assembler Packages, Emulators, Evaluation Boards, HLL-Debuggers, Simulators, Logic Analyzer Disassemblers, Programming Boards
- On-Chip Debug Support via JTAG Interface
- 100-Pin Green TQFP Package, 0.5 mm (19.7 mil) pitch (RoHS compliant)

Ordering Information

The ordering code for Infineon microcontrollers provides an exact reference to the required product. This ordering code identifies:

- the derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery.

For the available ordering codes for the XC164D please refer to your responsible sales representative or your local distributor.

Note: The ordering codes for Mask-ROM versions are defined for each product after verification of the respective ROM code.

This document describes several derivatives of the XC164D group. **Table 1** enumerates these derivatives and summarizes the differences. As this document refers to all of these derivatives, some descriptions may not apply to a specific product.

For simplicity all versions are referred to by the term **XC164D** throughout this document.

2.2 Pin Configuration and Definition

The pins of the XC164D are described in detail in **Table 2**, including all their alternate functions. **Figure 2** summarizes all pins in a condensed way, showing their location on the 4 sides of the package. E*) and C*) mark pins to be used as alternate external interrupt inputs, C*) marks pins that can have CAN interface lines assigned to them.

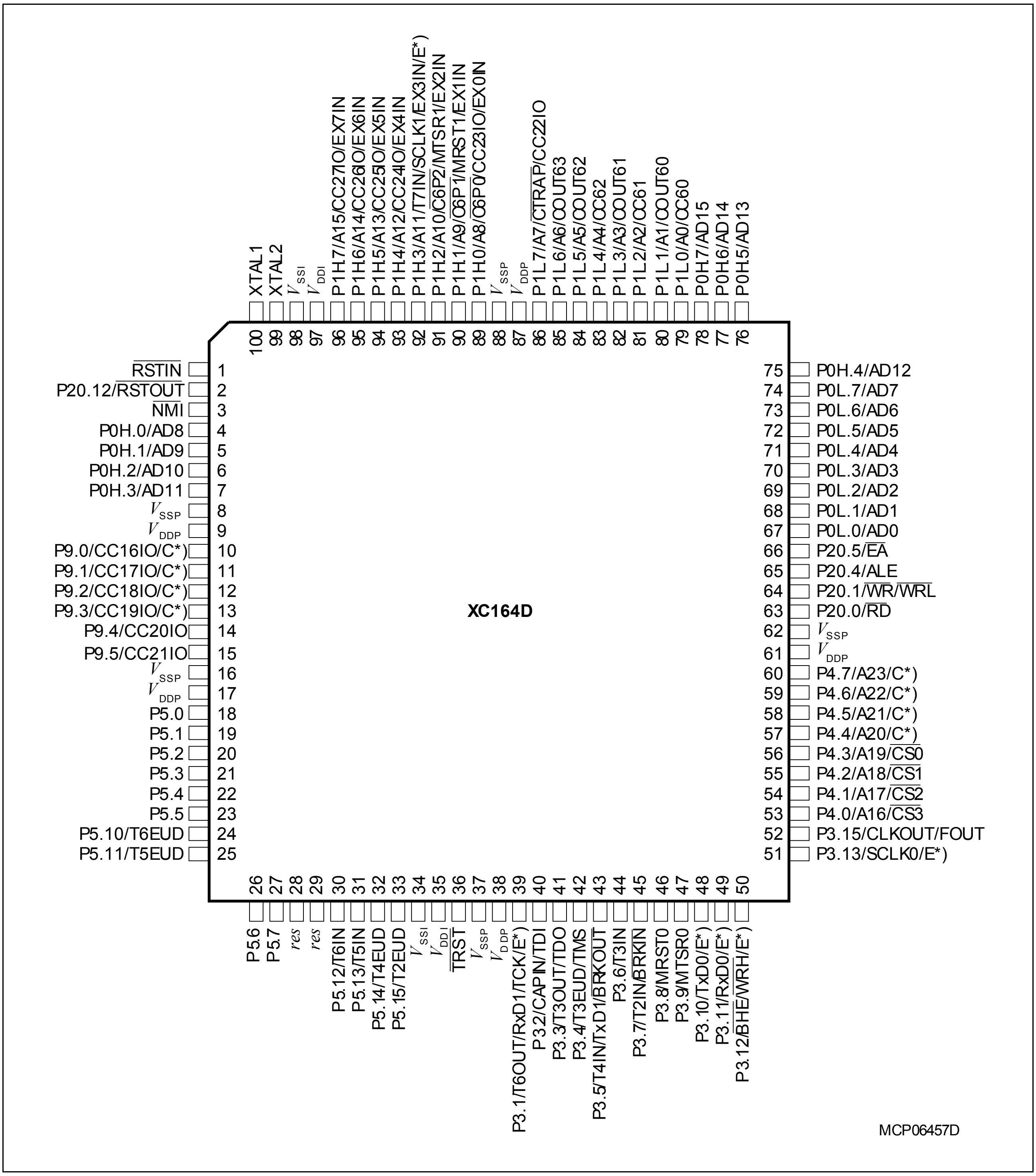

Figure 2 Pin Configuration (top view)

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Num.	Input Outp.	Function
P4		IO	Port 4 is an 8-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 4 is selectable (standard or special). Port 4 can be used to output the segment address lines, the optional chip select lines, and for serial interface lines:[1]
P4.0	53	O	A16 Least Significant Segment Address Line,
		O	$\overline{\text{CS3}}$ Chip Select 3 Output
P4.1	54	O	A17 Segment Address Line,
		O	$\overline{\text{CS2}}$ Chip Select 2 Output
P4.2	55	O	A18 Segment Address Line,
		O	$\overline{\text{CS1}}$ Chip Select 1 Output
P4.3	56	O	A19 Segment Address Line,
		O	$\overline{\text{CS0}}$ Chip Select 0 Output
P4.4	57	O	A20 Segment Address Line,
		I	CAN1_RxD CAN Node B Receive Data Input,
		I	EX5IN Fast External Interrupt 5 Input (alternate pin B)
P4.5	58	O	A21 Segment Address Line,
		I	CAN0_RxD CAN Node A Receive Data Input,
		I	EX4IN Fast External Interrupt 4 Input (alternate pin B)
P4.6	59	O	A22 Segment Address Line,
		O	CAN0_TxD CAN Node A Transmit Data Output,
		I	EX5IN Fast External Interrupt 5 Input (alternate pin A)
P4.7	60	O	A23 Most Significant Segment Address Line,
		I	CAN0_RxD CAN Node A Receive Data Input,
		O	CAN1_TxD CAN Node B Transmit Data Output,
		I	EX4IN Fast External Interrupt 4 Input (alternate pin A)

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Num.	Input Outp.	Function
P20		IO	Port 20 is a 5-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output. The input threshold of Port 20 is selectable (standard or special). The following Port 20 pins also serve for alternate functions:
P20.0	63	O	$\overline{\text{RD}}$ External Memory Read Strobe, activated for every external instruction or data read access.
P20.1	64	O	$\overline{\text{WR}}/\overline{\text{WRL}}$ External Memory Write Strobe. In $\overline{\text{WR}}$-mode this pin is activated for every external data write access. In $\overline{\text{WRL}}$-mode this pin is activated for low byte data write accesses on a 16-bit bus, and for every data write access on an 8-bit bus.
P20.4	65	O	ALE Address Latch Enable Output. Can be used for latching the address into external memory or an address latch in the multiplexed bus modes.
P20.5	66	I	$\overline{\text{EA}}$ External Access Enable pin. **A low level** at this pin during and after Reset forces the XC164D to latch the configuration from PORT0 and pin $\overline{\text{RD}}$, and to begin instruction execution out of external memory. **A high level** forces the XC164D to latch the configuration from pins $\overline{\text{RD}}$, ALE, and $\overline{\text{WR}}$, and to begin instruction execution out of the internal program memory. "ROMless" versions must have this pin tied to '0'.
P20.12	2	O	$\overline{\text{RSTOUT}}$ Internal Reset Indication Output. **Is activated** asynchronously with an external hardware reset. It may also be activated (selectable) synchronously with an internal software or watchdog reset. **Is deactivated** upon the execution of the EINIT instruction, optionally at the end of reset, or at any time (before EINIT) via user software.
			Note: Port 20 pins may input configuration values (see $\overline{\text{EA}}$).

3 Functional Description

The architecture of the XC164D combines advantages of RISC, CISC, and DSP processors with an advanced peripheral subsystem in a very well-balanced way. In addition, the on-chip memory blocks allow the design of compact systems-on-silicon with maximum performance (computing, control, communication).

The on-chip memory blocks (program code-memory and SRAM, dual-port RAM, data SRAM) and the set of generic peripherals are connected to the CPU via separate buses. Another bus, the LXBus, connects additional on-chip resources as well as external resources (see **Figure 3**).

This bus structure enhances the overall system performance by enabling the concurrent operation of several subsystems of the XC164D.

The following block diagram gives an overview of the different on-chip components and of the advanced, high bandwidth internal bus structure of the XC164D.

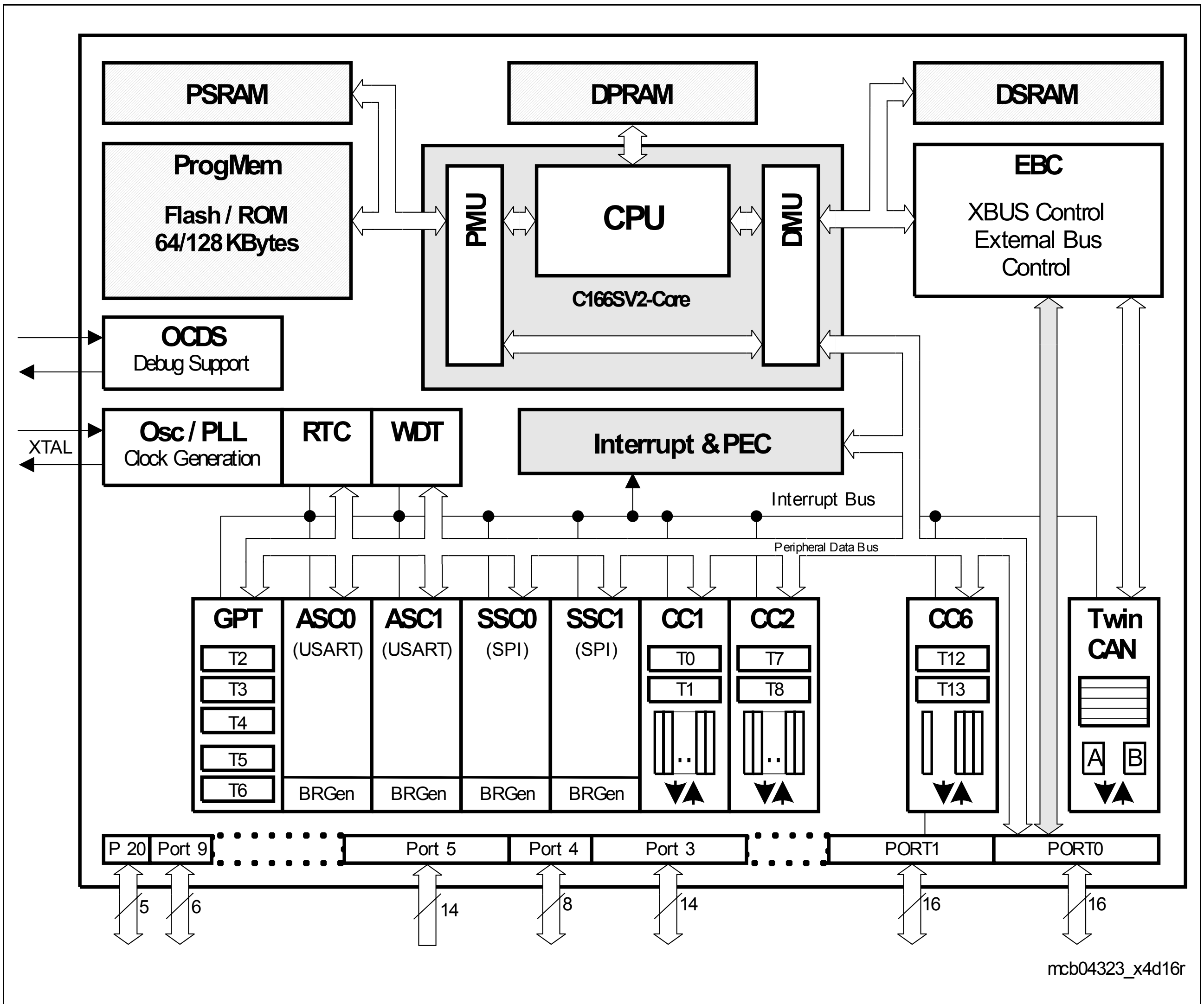

Figure 3 Block Diagram

example, shift and rotate instructions are always processed during one machine cycle independent of the number of bits to be shifted. Also multiplication and most MAC instructions execute in one single cycle. All multiple-cycle instructions have been optimized so that they can be executed very fast as well: for example, a division algorithm is performed in 18 to 21 CPU cycles, depending on the data and division type. Four cycles are always visible, the rest runs in the background. Another pipeline optimization, the branch target prediction, allows eliminating the execution time of branch instructions if the prediction was correct.

The CPU has a register context consisting of up to three register banks with 16 wordwide GPRs each at its disposal. The global register bank is physically allocated within the on-chip DPRAM area. A Context Pointer (CP) register determines the base address of the active global register bank to be accessed by the CPU at any time. The number of register banks is only restricted by the available internal RAM space. For easy parameter passing, a register bank may overlap others.

A system stack of up to 32 Kwords is provided as a storage for temporary data. The system stack can be allocated to any location within the address space (preferably in the on-chip RAM area), and it is accessed by the CPU via the stack pointer (SP) register. Two separate SFRs, STKOV and STKUN, are implicitly compared against the stack pointer value upon each stack access for the detection of a stack overflow or underflow.

The high performance offered by the hardware implementation of the CPU can efficiently be utilized by a programmer via the highly efficient XC164D instruction set which includes the following instruction classes:

- Standard Arithmetic Instructions
- DSP-Oriented Arithmetic Instructions
- Logical Instructions
- Boolean Bit Manipulation Instructions
- Compare and Loop Control Instructions
- Shift and Rotate Instructions
- Prioritize Instruction
- Data Movement Instructions
- System Stack Instructions
- Jump and Call Instructions
- Return Instructions
- System Control Instructions
- Miscellaneous Instructions

The basic instruction length is either 2 or 4 bytes. Possible operand types are bits, bytes and words. A variety of direct, indirect or immediate addressing modes are provided to specify the required operands.

Table 4 XC164D Interrupt Nodes

Source of Interrupt or PEC Service Request	Control Register	Vector Location[1]	Trap Number
CAPCOM Register 0	CC1_CC0IC	xx'0040$_H$	10$_H$ / 16$_D$
CAPCOM Register 1	CC1_CC1IC	xx'0044$_H$	11$_H$ / 17$_D$
CAPCOM Register 2	CC1_CC2IC	xx'0048$_H$	12$_H$ / 18$_D$
CAPCOM Register 3	CC1_CC3IC	xx'004C$_H$	13$_H$ / 19$_D$
CAPCOM Register 4	CC1_CC4IC	xx'0050$_H$	14$_H$ / 20$_D$
CAPCOM Register 5	CC1_CC5IC	xx'0054$_H$	15$_H$ / 21$_D$
CAPCOM Register 6	CC1_CC6IC	xx'0058$_H$	16$_H$ / 22$_D$
CAPCOM Register 7	CC1_CC7IC	xx'005C$_H$	17$_H$ / 23$_D$
CAPCOM Register 8	CC1_CC8IC	xx'0060$_H$	18$_H$ / 24$_D$
CAPCOM Register 9	CC1_CC9IC	xx'0064$_H$	19$_H$ / 25$_D$
CAPCOM Register 10	CC1_CC10IC	xx'0068$_H$	1A$_H$ / 26$_D$
CAPCOM Register 11	CC1_CC11IC	xx'006C$_H$	1B$_H$ / 27$_D$
CAPCOM Register 12	CC1_CC12IC	xx'0070$_H$	1C$_H$ / 28$_D$
CAPCOM Register 13	CC1_CC13IC	xx'0074$_H$	1D$_H$ / 29$_D$
CAPCOM Register 14	CC1_CC14IC	xx'0078$_H$	1E$_H$ / 30$_D$
CAPCOM Register 15	CC1_CC15IC	xx'007C$_H$	1F$_H$ / 31$_D$
CAPCOM Register 16	CC2_CC16IC	xx'00C0$_H$	30$_H$ / 48$_D$
CAPCOM Register 17	CC2_CC17IC	xx'00C4$_H$	31$_H$ / 49$_D$
CAPCOM Register 18	CC2_CC18IC	xx'00C8$_H$	32$_H$ / 50$_D$
CAPCOM Register 19	CC2_CC19IC	xx'00CC$_H$	33$_H$ / 51$_D$
CAPCOM Register 20	CC2_CC20IC	xx'00D0$_H$	34$_H$ / 52$_D$
CAPCOM Register 21	CC2_CC21IC	xx'00D4$_H$	35$_H$ / 53$_D$
CAPCOM Register 22	CC2_CC22IC	xx'00D8$_H$	36$_H$ / 54$_D$
CAPCOM Register 23	CC2_CC23IC	xx'00DC$_H$	37$_H$ / 55$_D$
CAPCOM Register 24	CC2_CC24IC	xx'00E0$_H$	38$_H$ / 56$_D$
CAPCOM Register 25	CC2_CC25IC	xx'00E4$_H$	39$_H$ / 57$_D$
CAPCOM Register 26	CC2_CC26IC	xx'00E8$_H$	3A$_H$ / 58$_D$
CAPCOM Register 27	CC2_CC27IC	xx'00EC$_H$	3B$_H$ / 59$_D$
CAPCOM Register 28	CC2_CC28IC	xx'00F0$_H$	3C$_H$ / 60$_D$

Table 4 XC164D Interrupt Nodes (cont'd)

Source of Interrupt or PEC Service Request	Control Register	Vector Location[1]	Trap Number
CAPCOM Register 29	CC2_CC29IC	xx'0110$_H$	44$_H$ / 68$_D$
CAPCOM Register 30	CC2_CC30IC	xx'0114$_H$	45$_H$ / 69$_D$
CAPCOM Register 31	CC2_CC31IC	xx'0118$_H$	46$_H$ / 70$_D$
CAPCOM Timer 0	CC1_T0IC	xx'0080$_H$	20$_H$ / 32$_D$
CAPCOM Timer 1	CC1_T1IC	xx'0084$_H$	21$_H$ / 33$_D$
CAPCOM Timer 7	CC2_T7IC	xx'00F4$_H$	3D$_H$ / 61$_D$
CAPCOM Timer 8	CC2_T8IC	xx'00F8$_H$	3E$_H$ / 62$_D$
GPT1 Timer 2	GPT12E_T2IC	xx'0088$_H$	22$_H$ / 34$_D$
GPT1 Timer 3	GPT12E_T3IC	xx'008C$_H$	23$_H$ / 35$_D$
GPT1 Timer 4	GPT12E_T4IC	xx'0090$_H$	24$_H$ / 36$_D$
GPT2 Timer 5	GPT12E_T5IC	xx'0094$_H$	25$_H$ / 37$_D$
GPT2 Timer 6	GPT12E_T6IC	xx'0098$_H$	26$_H$ / 38$_D$
GPT2 CAPREL Register	GPT12E_CRIC	xx'009C$_H$	27$_H$ / 39$_D$
Unassigned node	–	xx'00A0$_H$	28$_H$ / 40$_D$
Unassigned node	–	xx'00A4$_H$	29$_H$ / 41$_D$
ASC0 Transmit	ASC0_TIC	xx'00A8$_H$	2A$_H$ / 42$_D$
ASC0 Transmit Buffer	ASC0_TBIC	xx'011C$_H$	47$_H$ / 71$_D$
ASC0 Receive	ASC0_RIC	xx'00AC$_H$	2B$_H$ / 43$_D$
ASC0 Error	ASC0_EIC	xx'00B0$_H$	2C$_H$ / 44$_D$
ASC0 Autobaud	ASC0_ABIC	xx'017C$_H$	5F$_H$ / 95$_D$
SSC0 Transmit	SSC0_TIC	xx'00B4$_H$	2D$_H$ / 45$_D$
SSC0 Receive	SSC0_RIC	xx'00B8$_H$	2E$_H$ / 46$_D$
SSC0 Error	SSC0_EIC	xx'00BC$_H$	2F$_H$ / 47$_D$
PLL/OWD	PLLIC	xx'010C$_H$	43$_H$ / 67$_D$
ASC1 Transmit	ASC1_TIC	xx'0120$_H$	48$_H$ / 72$_D$
ASC1 Transmit Buffer	ASC1_TBIC	xx'0178$_H$	5E$_H$ / 94$_D$
ASC1 Receive	ASC1_RIC	xx'0124$_H$	49$_H$ / 73$_D$
ASC1 Error	ASC1_EIC	xx'0128$_H$	4A$_H$ / 74$_D$
ASC1 Autobaud	ASC1_ABIC	xx'0108$_H$	42$_H$ / 66$_D$
End of PEC Subchannel	EOPIC	xx'0130$_H$	4C$_H$ / 76$_D$

The XC164D also provides an excellent mechanism to identify and to process exceptions or error conditions that arise during run-time, so-called 'Hardware Traps'. Hardware traps cause immediate non-maskable system reaction which is similar to a standard interrupt service (branching to a dedicated vector table location). The occurrence of a hardware trap is additionally signified by an individual bit in the trap flag register (TFR). Except when another higher prioritized trap service is in progress, a hardware trap will interrupt any actual program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

Table 5 shows all of the possible exceptions or error conditions that can arise during run-time:

Table 5 Hardware Trap Summary

Exception Condition	Trap Flag	Trap Vector	Vector Location[1]	Trap Number	Trap Priority
Reset Functions:	–				
• Hardware Reset		RESET	xx'0000$_H$	00$_H$	III
• Software Reset		RESET	xx'0000$_H$	00$_H$	III
• Watchdog Timer Overflow		RESET	xx'0000$_H$	00$_H$	III
Class A Hardware Traps:					
• Non-Maskable Interrupt	NMI	NMITRAP	xx'0008$_H$	02$_H$	II
• Stack Overflow	STKOF	STOTRAP	xx'0010$_H$	04$_H$	II
• Stack Underflow	STKUF	STUTRAP	xx'0018$_H$	06$_H$	II
• Software Break	SOFTBRK	SBRKTRAP	xx'0020$_H$	08$_H$	II
Class B Hardware Traps:					
• Undefined Opcode	UNDOPC	BTRAP	xx'0028$_H$	0A$_H$	I
• PMI Access Error	PACER	BTRAP	xx'0028$_H$	0A$_H$	I
• Protected Instruction Fault	PRTFLT	BTRAP	xx'0028$_H$	0A$_H$	I
• Illegal Word Operand Access	ILLOPA	BTRAP	xx'0028$_H$	0A$_H$	I
Reserved	–	–	[2C$_H$ - 3C$_H$]	[0B$_H$ - 0F$_H$]	–
Software Traps • TRAP Instruction	–	–	Any [xx'0000$_H$ - xx'01FC$_H$] in steps of 4$_H$	Any [00$_H$ - 7F$_H$]	Current CPU Priority

1) Register VECSEG defines the segment where the vector table is located to.

3.5 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system provides a broad range of debug and emulation features built into the XC164D. The user software running on the XC164D can thus be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface, consisting of the IEEE-1149-conforming JTAG port and a break interface. The debugger controls the OCDS via a set of dedicated registers accessible via the JTAG interface. Additionally, the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported as well as the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU-halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the JTAG interface or via the external bus interface for increased performance.

The debug interface uses a set of 6 interface signals (4 JTAG lines, 2 break lines) to communicate with external circuitry. These interface signals are realized as alternate functions on Port 3 pins.

Complete system emulation is supported by the New Emulation Technology (NET) interface.

3.6 Capture/Compare Units (CAPCOM1/2)

The CAPCOM units support generation and control of timing sequences on up to 32 channels with a maximum resolution of 1 system clock cycle (8 cycles in staggered mode). The CAPCOM units are typically used to handle high speed I/O tasks such as pulse and waveform generation, pulse width modulation (PMW), Digital to Analog (D/A) conversion, software timing, or time recording relative to external events.

Four 16-bit timers (T0/T1, T7/T8) with reload registers provide two independent time bases for each capture/compare register array.

The input clock for the timers is programmable to several prescaled values of the internal system clock, or may be derived from an overflow/underflow of timer T6 in module GPT2. This provides a wide range of variation for the timer period and resolution and allows precise adjustments to the application specific requirements. In addition, external count inputs for CAPCOM timers T0 and T7 allow event scheduling for the capture/compare registers relative to external events.

Both of the two capture/compare register arrays contain 16 dual purpose capture/compare registers, each of which may be individually allocated to either CAPCOM timer T0 or T1 (T7 or T8, respectively), and programmed for capture or

compare function.
12 registers of the CAPCOM2 module have each one port pin associated with it which serves as an input pin for triggering the capture function, or as an output pin to indicate the occurrence of a compare event.

Table 6 Compare Modes (CAPCOM1/2)

Compare Modes	Function
Mode 0	Interrupt-only compare mode; several compare interrupts per timer period are possible
Mode 1	Pin toggles on each compare match; several compare events per timer period are possible
Mode 2	Interrupt-only compare mode; only one compare interrupt per timer period is generated
Mode 3	Pin set '1' on match; pin reset '0' on compare timer overflow; only one compare event per timer period is generated
Double Register Mode	Two registers operate on one pin; pin toggles on each compare match; several compare events per timer period are possible
Single Event Mode	Generates single edges or pulses; can be used with any compare mode

When a capture/compare register has been selected for capture mode, the current contents of the allocated timer will be latched ('captured') into the capture/compare register in response to an external event at the port pin which is associated with this register. In addition, a specific interrupt request for this capture/compare register is generated. Either a positive, a negative, or both a positive and a negative external signal transition at the pin can be selected as the triggering event.

The contents of all registers which have been selected for one of the five compare modes are continuously compared with the contents of the allocated timers.

When a match occurs between the timer value and the value in a capture/compare register, specific actions will be taken based on the selected compare mode.

3.7 The Capture/Compare Unit (CAPCOM6)

The CAPCOM6 unit supports generation and control of timing sequences on up to three 16-bit capture/compare channels plus one independent 10-bit compare channel.
In compare mode the CAPCOM6 unit provides two output signals per channel which have inverted polarity and non-overlapping pulse transitions (deadtime control). The compare channel can generate a single PWM output signal and is further used to modulate the capture/compare output signals.
In capture mode the contents of compare timer T12 is stored in the capture registers upon a signal transition at pins CCx.

Compare timers T12 (16-bit) and T13 (10-bit) are free running timers which are clocked by the prescaled system clock.

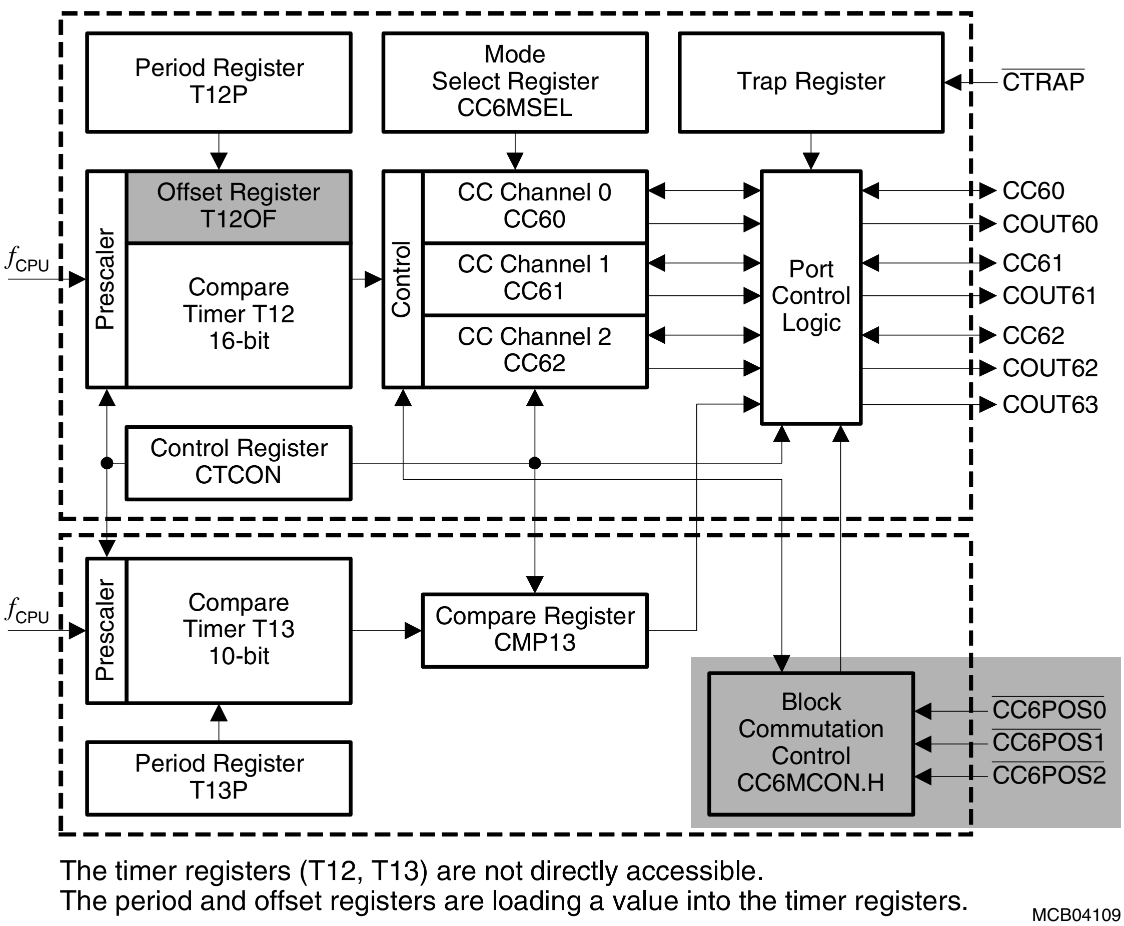

Figure 6 CAPCOM6 Block Diagram

For motor control applications both subunits may generate versatile multichannel PWM signals which are basically either controlled by compare timer T12 or by a typical hall sensor pattern at the interrupt inputs (block commutation).

3.8 General Purpose Timer Unit (GPT12E)

The GPT12E unit represents a very flexible multifunctional timer/counter structure which may be used for many different time related tasks such as event timing and counting, pulse width and duty cycle measurements, pulse generation, or pulse multiplication.

The GPT12E unit incorporates five 16-bit timers which are organized in two separate modules, GPT1 and GPT2. Each timer in each module may operate independently in a number of different modes, or may be concatenated with another timer of the same module.

Each of the three timers T2, T3, T4 of **module GPT1** can be configured individually for one of four basic modes of operation, which are Timer, Gated Timer, Counter, and Incremental Interface Mode. In Timer Mode, the input clock for a timer is derived from the system clock, divided by a programmable prescaler, while Counter Mode allows a timer to be clocked in reference to external events.
Pulse width or duty cycle measurement is supported in Gated Timer Mode, where the operation of a timer is controlled by the 'gate' level on an external input pin. For these purposes, each timer has one associated port pin (TxIN) which serves as gate or clock input. The maximum resolution of the timers in module GPT1 is 4 system clock cycles.

The count direction (up/down) for each timer is programmable by software or may additionally be altered dynamically by an external signal on a port pin (TxEUD) to facilitate e.g. position tracking.

In Incremental Interface Mode the GPT1 timers (T2, T3, T4) can be directly connected to the incremental position sensor signals A and B via their respective inputs TxIN and TxEUD. Direction and count signals are internally derived from these two input signals, so the contents of the respective timer Tx corresponds to the sensor position. The third position sensor signal TOP0 can be connected to an interrupt input.

Timer T3 has an output toggle latch (T3OTL) which changes its state on each timer overflow/underflow. The state of this latch may be output on pin T3OUT e.g. for time out monitoring of external hardware components. It may also be used internally to clock timers T2 and T4 for measuring long time periods with high resolution.

In addition to their basic operating modes, timers T2 and T4 may be configured as reload or capture registers for timer T3. When used as capture or reload registers, timers T2 and T4 are stopped. The contents of timer T3 is captured into T2 or T4 in response to a signal at their associated input pins (TxIN). Timer T3 is reloaded with the contents of T2 or T4 triggered either by an external signal or by a selectable state transition of its toggle latch T3OTL. When both T2 and T4 are configured to alternately reload T3 on opposite state transitions of T3OTL with the low and high times of a PWM signal, this signal can be constantly generated without software intervention.

count direction (up/down) for each timer is programmable by software or may additionally be altered dynamically by an external signal on a port pin (TxEUD). Concatenation of the timers is supported via the output toggle latch (T6OTL) of timer T6, which changes its state on each timer overflow/underflow.

The state of this latch may be used to clock timer T5, and/or it may be output on pin T6OUT. The overflows/underflows of timer T6 can additionally be used to clock the CAPCOM1/2 timers, and to cause a reload from the CAPREL register.

The CAPREL register may capture the contents of timer T5 based on an external signal transition on the corresponding port pin (CAPIN), and timer T5 may optionally be cleared after the capture procedure. This allows the XC164D to measure absolute time differences or to perform pulse multiplication without software overhead.

The capture trigger (timer T5 to CAPREL) may also be generated upon transitions of GPT1 timer T3's inputs T3IN and/or T3EUD. This is especially advantageous when T3 operates in Incremental Interface Mode.

Table 7 Summary of the XC164D's Parallel Ports

Port	Control	Alternate Functions
PORT0	Pad drivers	Address/Data lines or data lines[1]
PORT1	Pad drivers	Address lines[2]
		Capture inputs or compare outputs, Serial interface lines, Fast external interrupt inputs
Port 3	Pad drivers, Open drain, Input threshold	Timer control signals, serial interface lines, Optional bus control signal $\overline{\text{BHE}}$/$\overline{\text{WRH}}$, System clock output CLKOUT (or FOUT), Debug interface lines
Port 4	Pad drivers, Open drain, Input threshold	Segment address lines[3]
		Optional chip select signals
		CAN interface lines[4]
Port 5	–	Timer control signals
Port 9	Pad drivers, Open drain, Input threshold	Capture inputs or compare outputs
		CAN interface lines[4]
Port 20	Pad drivers, Open drain	Bus control signals $\overline{\text{RD}}$, $\overline{\text{WR}}$/$\overline{\text{WRL}}$, ALE, External access enable pin $\overline{\text{EA}}$, Reset indication output $\overline{\text{RSTOUT}}$

1) For multiplexed bus cycles.
2) For demultiplexed bus cycles.
3) For more than 64 Kbytes of external resources.
4) Can be assigned by software.

4.2 DC Parameters

Table 11 DC Characteristics (Operating Conditions apply)[1)]

Parameter	Symbol		Limit Values		Unit	Test Condition
			Min.	Max.		
Input low voltage TTL (all except XTAL1)	V_{IL}	SR	-0.5	$0.2 \times V_{DDP}$ - 0.1	V	–
Input low voltage XTAL1[2)]	V_{ILC}	SR	-0.5	$0.3 \times V_{DDI}$	V	–
Input low voltage (Special Threshold)	V_{ILS}	SR	-0.5	$0.45 \times V_{DDP}$	V	[3)]
Input high voltage TTL (all except XTAL1)	V_{IH}	SR	$0.2 \times V_{DDP}$ + 0.9	V_{DDP} + 0.5	V	–
Input high voltage XTAL1[2)]	V_{IHC}	SR	$0.7 \times V_{DDI}$	V_{DDI} + 0.5	V	–
Input high voltage (Special Threshold)	V_{IHS}	SR	$0.8 \times V_{DDP}$ - 0.2	V_{DDP} + 0.5	V	[3)]
Input Hysteresis (Special Threshold)	HYS		$0.04 \times V_{DDP}$	–	V	V_{DDP} in [V], Series resistance = 0 Ω[3)]
Output low voltage	V_{OL}	CC	–	1.0	V	$I_{OL} \leq I_{OLmax}$[4)]
			–	0.45	V	$I_{OL} \leq I_{OLnom}$[4)5)]
Output high voltage[6)]	V_{OH}	CC	V_{DDP} - 1.0	–	V	$I_{OH} \geq I_{OHmax}$[4)]
			V_{DDP} - 0.45	–	V	$I_{OH} \geq I_{OHnom}$[4)5)]
Input leakage current (Port 5)[7)]	I_{OZ1}	CC	–	±300	nA	0 V < V_{IN} < V_{DDP}, $T_A \leq$ 125 °C
				±200	nA	0 V < V_{IN} < V_{DDP}, $T_A \leq$ 85 °C[14)]
Input leakage current (all other[8)])[7)]	I_{OZ2}	CC	–	±500	nA	0.45 V < V_{IN} < V_{DDP}
Configuration pull-up current[9)]	I_{CPUH}[10)]		–	-10	µA	$V_{IN} = V_{IHmin}$
	I_{CPUL}[11)]		-100	–	µA	$V_{IN} = V_{ILmax}$
Configuration pull-down current[12)]	I_{CPDL}[10)]		–	10	µA	$V_{IN} = V_{ILmax}$
	I_{CPDH}[11)]		120	–	µA	$V_{IN} = V_{IHmin}$

1) An output current above $|I_{OXnom}|$ may be drawn from up to three pins at the same time.
For any group of 16 neighboring port output pins the total output current in each direction (ΣI_{OL} and $\Sigma\text{-}I_{OH}$) must remain below 50 mA.

Table 13 Power Consumption XC164D (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		Min.	Max.		
Power supply current (active) with all peripherals active	I_{DDI}	–	15 + 2.6 $\times f_{CPU}$	mA	f_{CPU} in [MHz][1)2)]
Pad supply current	I_{DDP}	–	5	mA	[3)]
Idle mode supply current with all peripherals active	I_{IDX}	–	15 + 1.2 $\times f_{CPU}$	mA	f_{CPU} in [MHz][2)]
Sleep and Power down mode supply current caused by leakage[4)]	I_{PDL}[5)]	–	128,000 $\times e^{-\alpha}$	mA	$V_{DDI} = V_{DDImax}$[6)] T_J in [°C] α = 4670 / (273 + T_J)
Sleep and Power down mode supply current caused by leakage and the RTC running, clocked by the main oscillator[4)]	I_{PDM}[7)]	–	0.6 + 0.02 $\times f_{OSC}$ + I_{PDL}	mA	$V_{DDI} = V_{DDImax}$ f_{OSC} in [MHz]

1) During Flash programming or erase operations the supply current is increased by max. 5 mA.
2) The supply current is a function of the operating frequency. This dependency is illustrated in **Figure 11**. These parameters are tested at V_{DDImax} and maximum CPU clock frequency with all outputs disconnected and all inputs at V_{IL} or V_{IH}.
3) The pad supply voltage pins (V_{DDP}) mainly provides the current consumed by the pin output drivers. A small amount of current is consumed even though no outputs are driven, because the drivers' input stages are switched and also the Flash module draws some power from the V_{DDP} supply.
4) The total supply current in Sleep and Power down mode is the sum of the temperature dependent leakage current and the frequency dependent current for RTC and main oscillator (if active).
5) This parameter is determined mainly by the transistor leakage currents. This current heavily depends on the junction temperature (see **Figure 13**). The junction temperature T_J is the same as the ambient temperature T_A if no current flows through the port output drivers. Otherwise, the resulting temperature difference must be taken into account.
6) All inputs (including pins configured as inputs) at 0 V to 0.1 V or at V_{DDP} - 0.1 V to V_{DDP}, all outputs (including pins configured as outputs) disconnected. This parameter is tested at 25 °C and is valid for $T_J \geq 25$ °C.
7) This parameter is determined mainly by the current consumed by the oscillator switched to low gain mode (see **Figure 12**). This current, however, is influenced by the external oscillator circuitry (crystal, capacitors). The given values refer to a typical circuitry and may change in case of a not optimized external oscillator circuitry.

Variable Memory Cycles

External bus cycles of the XC164D are executed in five subsequent cycle phases (AB, C, D, E, F). The duration of each cycle phase is programmable (via the TCONCSx registers) to adapt the external bus cycles to the respective external module (memory, peripheral, etc.).

This table provides a summary of the phases and the respective choices for their duration.

Table 19 Programmable Bus Cycle Phases (see timing diagrams)

Bus Cycle Phase	Parameter	Valid Values	Unit
Address setup phase, the standard duration of this phase (1 … 2 TCP) can be extended by 0 … 3 TCP if the address window is changed	tp_{AB}	1 … 2 (5)	TCP
Command delay phase	tp_{C}	0 … 3	TCP
Write Data setup/MUX Tristate phase	tp_{D}	0 … 1	TCP
Access phase	tp_{E}	1 … 32	TCP
Address/Write Data hold phase	tp_{F}	0 … 3	TCP

Note: The bandwidth of a parameter (minimum and maximum value) covers the whole operating range (temperature, voltage) as well as process variations. Within a given device, however, this bandwidth is smaller than the specified range. This is also due to interdependencies between certain parameters. Some of these interdependencies are described in additional notes (see standard timing).

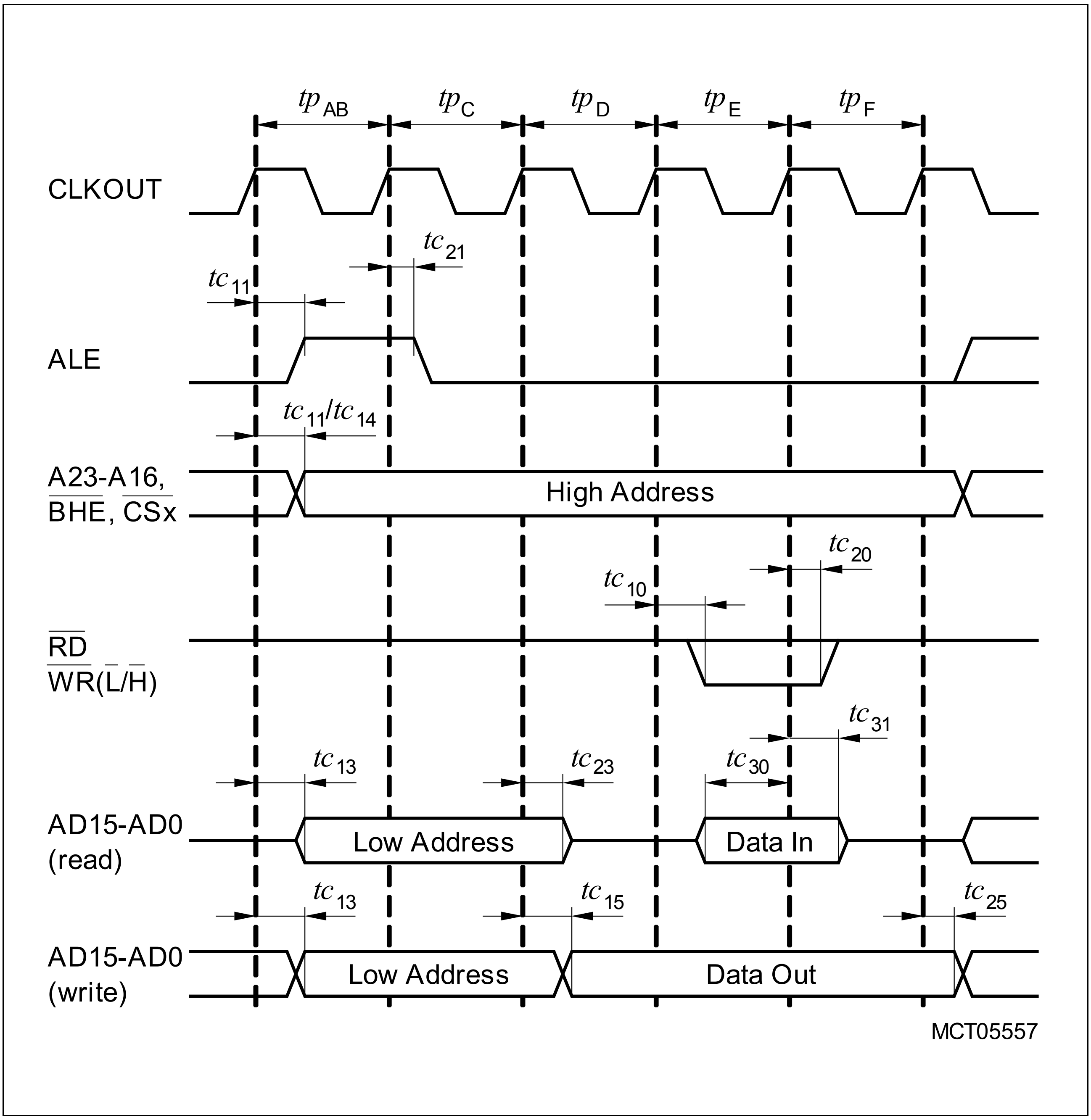

Figure 20 Multiplexed Bus Cycle